

Electronic Patent Application Fee Transmittal				
Application Number:		10537509		
Filing Date:		30-Nov-2005		
Title of Invention:		Method for cutting semiconductor substrate		
First Named Inventor/Applicant Name:		Fumitsugu Fukuyo		
Filer:		John G. Smith/Traci N. Thompson		
Attorney Docket Number:		46884-5388 (211285)		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180